

```

ISNR:
ISNR:
BRS:
BRS: bios

```

 Pending

 Active

```

L1: (4230) ic same thermal
L2: (2) adaptive same 1
L3: (265) ic and (thermal adj4 manage$5)
L4: (27) overclock$3
L6: (0) 1 and 4
L7: (0) 3 and 4
L5: (107) 1 and 3
L8: (8100) bios
L9: (6) 4 and 8
L10: (2) 3 and 8
L11: (1) "5825972".PN.
L12: (1) "5460009".PN.
L13: (1) "5457766".PN.
L14: (1) "5197858".PN.
L15: (1) "5099181".PN.
L16: (1) "4168456".PN.
L17: (7) overclock$3 and (thermal adj4 manage$5)

```

**Failed**

 Saved

## Favorites

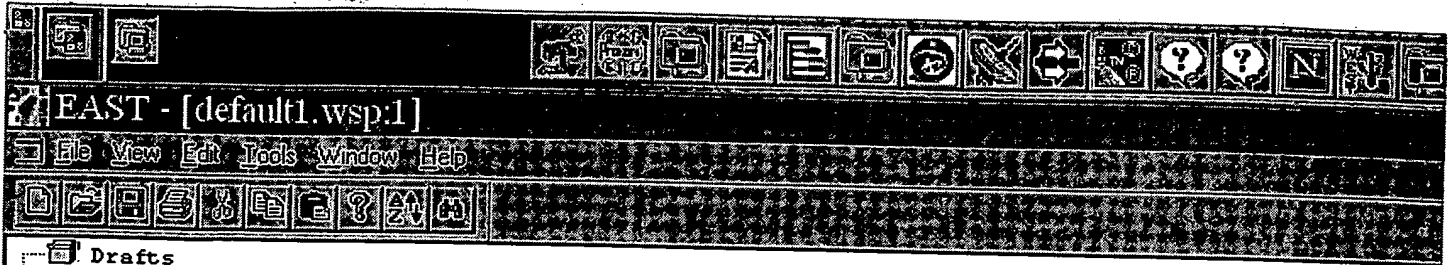
Tagged (0)

 **VDC**

 Queue

 **Trash**

	U	1	Document ID	Issue Date	Pages	Title
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6587514 B1	20030701	95	Digital predistortion methods for wideband amplifiers
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6535988 B1	20030318	15	System for detecting over-clocking uses a reference signal thereafter preventing over-clocking by reducing clock rate
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6476670 B2	20021105	94	Amplifier measurement and modeling processes for use in generating predistortion parameters
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6459334 B2	20021001	193	Amplifier measurement and modeling processes for use in generating predistortion parameters



- ☐ Drafts
- ☐ Pending
- ☐ Active
  - ☐ L1: (765) power same thermal adj management
  - ☐ L2: (35) bios and 1
  - ☐ L3: (7) bios same 1
- ☐ Failed
- ☐ Saved
- ☐ Favorites
- ☐ Tagged (0)
- ☐ UDC
- ☐ Queue
- ☐ Trash

	U	S	Document ID	Issue Date	Pages	Title
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6654783 B1	20031125	21	Network site content indexing method and associated system
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6535988 B1	20030318	15	System for detecting over-clocking uses a reference signal thereafter preventing

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((thermal management and ic) and ((1950 <in> py) or (1951 <in> py) or (1952 <in> py)

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